

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	84	"6100594"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:38
L2	2614151	controller microprocessor CPU processor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:39
L3	254	stacked with memory with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:43
L4	193	3 and 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/27 11:43

 PALM IntranetApplication Number

IDS Flag Clearance for Application 10809720

**IDS
Information**

Content	Mailroom Date	Entry Number	IDS Review	Last Modified	Reviewer
M844	2006-08-09	33	Y <input checked="" type="checkbox"/>	2006-10-27 12:25:14.0	TNguyen31
M844	2004-03-25	13	Y <input checked="" type="checkbox"/>	2006-03-05 19:45:21.0	TNguyen31
<input type="button" value="Update"/>					

EAST - [thinnew2.wsp:1]

File View Edit Tools Window Help

- S644: (369894) multilayer\$2 multi adj layer\$2
- S658: (327126) S635 S636 S637
- S659: (12) "6538331"
- S660: (2) "20050212144"
- S661: (0) die adj to adj die same connector
- S663: (949) die-to-die
- S662: (0) die adj to adj die
- S664: (2) S663 same connector
- S665: (236) S663 and memory and controller
- S667: (93) S663 and S666
- S666: (31982) wire near bond

Favorites

Search

US-PG-PUB;USPAT;EPD;JPO;DERMENT;IBM;TDB

Default operator: OR

S663 and S666

Buttons: Browse, Download, Print, etc.

Options: Exact, Highlight all hits in body

BRS form

IS&R form

Image

Text

HTML

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cla	Inventor	S	C	P	2	3	Image I
47	<input type="checkbox"/>	<input type="checkbox"/>	US 7023077 B2	20060404	23	Carrier with metal bumps for semiconductor die packages	257/678	257/679; 257/680;		Madrid, Ruben	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 7023
48	<input type="checkbox"/>	<input type="checkbox"/>	US 7018867 B2	20060328	7	Fabricating stacked chips using fluidic templated assembly	438/110	257/723; 257/E21.705		Gracias, David	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 7018
49	<input type="checkbox"/>	<input type="checkbox"/>	US 7015587 B1	20060321	11	Stacked die package for semiconductor devices	257/777	257/666; 257/685;		Poddar, Anindya	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 7015
50	<input type="checkbox"/>	<input type="checkbox"/>	US 6998292 B2	20060214	11	Apparatus and method for inter-chip or chip-to-substrate connection with integrated circuit package having reduced interconnects	438/107	257/685; 257/686;		McDonough, Robert J. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6998
51	<input type="checkbox"/>	<input type="checkbox"/>	US 6979904 B2	20051227	8	Semiconductor dice packages employing at least one redistribution layer	257/777	257/734; 257/780;		Farnworth, Warren M. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6979
52	<input type="checkbox"/>	<input type="checkbox"/>	US 6965160 B2	20051115	17	Apparatus for routing die interconnections using intermediate connection bonding wire	257/686	257/685; 257/698;		Cobbley, Chad A. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6965
53	<input type="checkbox"/>	<input type="checkbox"/>	US 6956294 B2	20051018	17	Flip chip in leaded molded package and method of manufacture thereof	257/786	257/E23.02; 257/E23.021;		Ball, Michael B.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6956
54	<input type="checkbox"/>	<input type="checkbox"/>	US 6949410 B2	20050927	16	Ultra-low loop wire bonding	438/111	138/112; 138/116;		Joshi, Rajeev et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6949
55	<input type="checkbox"/>	<input type="checkbox"/>	US 6933223 B1	20050823	12	Assemblies and packages including die-to-die connections	438/617	257/724; 257/777;		Soon, Lim Peng et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6933
56	<input type="checkbox"/>	<input type="checkbox"/>	US 6906408 B2	20050614	16	Method of packaging semiconductor dice employing at least one redistribution layer	257/686	257/E21.502; 257/E21.512;		Cloud, Eugene H. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6906
57	<input type="checkbox"/>	<input type="checkbox"/>	US 6897096 B2	20050524	17	Carrier with metal bumps for semiconductor die packages	438/123	257/E23.069; 438/666;		Cobbley, Chad A. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6897
58	<input type="checkbox"/>	<input type="checkbox"/>	US 6893901 B2	20050517	22	Stacked dies utilizing cross connection bonding wire	438/122	257/735; 257/776;		Madrid, Ruben	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6893
59	<input type="checkbox"/>	<input type="checkbox"/>	US 6787901 B2	20040907	12	Flip chip in leaded molded package and method of manufacture thereof	257/724	257/502; 257/578;		Reyes, Edward et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6787
60	<input type="checkbox"/>	<input type="checkbox"/>	US 6720642 B1	20040413	17	Method and apparatus for die stacking	257/673	257/E25.011;		Joshi, Rajeev et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6720
61	<input type="checkbox"/>	<input type="checkbox"/>	US 6680219 B2	20040120	11	Method for routing die interconnections using intermediate connection bonding wire	438 109	228 180.5;		Reyes, Edward et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6680
62	<input type="checkbox"/>	<input type="checkbox"/>	US 6630372 B2	20031007	17	Making leadframe semiconductor	438/123	257/E23.02; 257/E23.021;		Ball, Michael B.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6630
63	<input type="checkbox"/>	<input type="checkbox"/>	US 6603072 B1	20030805	8		174/536	257/686;		Foster, Donald C. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6603

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Details

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